

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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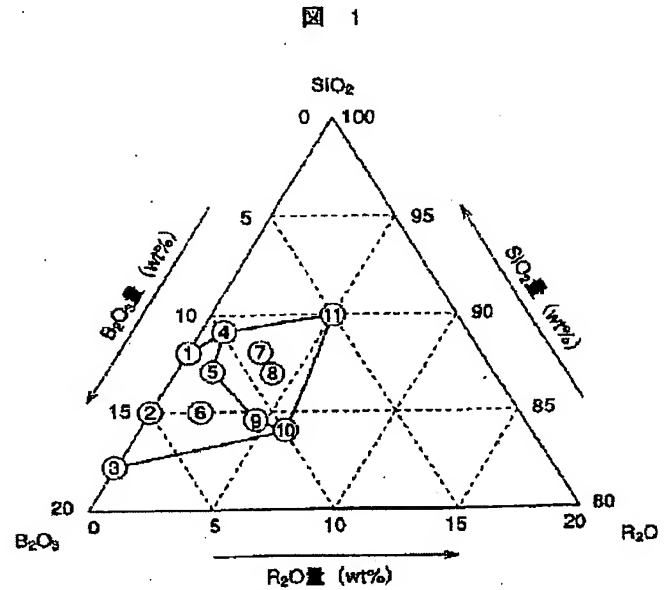
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APPLICANT : HITACHI LTD;

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TITLE : AMORPHOUS GLASS



ABSTRACT : PROBLEM TO BE SOLVED: To provide a ceramic wiring board sintered at 900-1050°C which has a small dielectric constant, small coefficient of thermal expansion matching with silicon and large bending strength.

- SOLUTION: Glass with softening temperature 850-1100°C i.e., in the Fig. 1 (SiO<sub>2</sub>-B<sub>2</sub>O<sub>3</sub>-R<sub>2</sub>O triangle composition chart. Positions of small circlets express each composition and the figures in the small circlets express composition numbers), the glass having compositions expressed by points in the territory (including an on-line) enclosed by lines connecting each point which express the first, the third, the tenth, the eleventh and the fourth compositions, are raw materials of the glass. Aqueous dispersion type grain is used as a binder, and in the firing process a green sheet is compressed in the direction of thickness.

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